

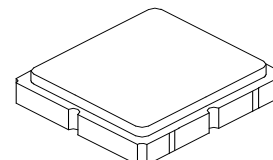
- **Surface Mount 3.0 x 3.0 mm Package**
- **Complies with Directive 2002/95/EC (RoHS)**
- **Moisture Sensitivity Level: 1**
- **AEC-Q200 Qualified**

Absolute Maximum Ratings

Rating	Value	Units
Input Power Level	10	dBm
DC Voltage on any Non-ground Terminal	3	V
Operable Temperature Range	-45 to +125	°C
Specification Temperature Range	-40 to +105	°C
Storage Temperature Range in Tape and Reel	-40 to +85	°C

SF2393E

**1570 MHz
SAW Filter**



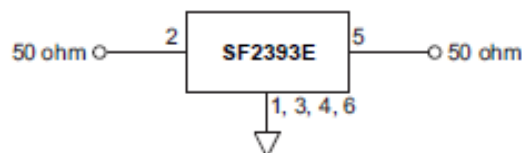
SM3030-6

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	f_c			1570		MHz
Insertion Loss, (1530 to 1610 MHz)	IL			3.6	4.2	dB
Pass Band Ripple, (1530 to 1610 MHz)				1.3	2.2	
Group Delay Variation (1530 to 1610 MHz)				4	30	ns
Return Loss (1530 to 1610 MHz)			6	7.5		dB
Attenuation, Referenced from 0 dB:						
50 to 1370 MHz			20	28		dB
1700 to 2000 MHz			10	24		
Temperature coefficient of frequency				-80		Ppm/°C
Case Style	SM3030-6 3.0 x 3.0 mm Nominal Footprint					
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	6Z, YWWS					

Electrical Connections

Connection	Terminals
Input	2
Output	5
Case Ground	All others

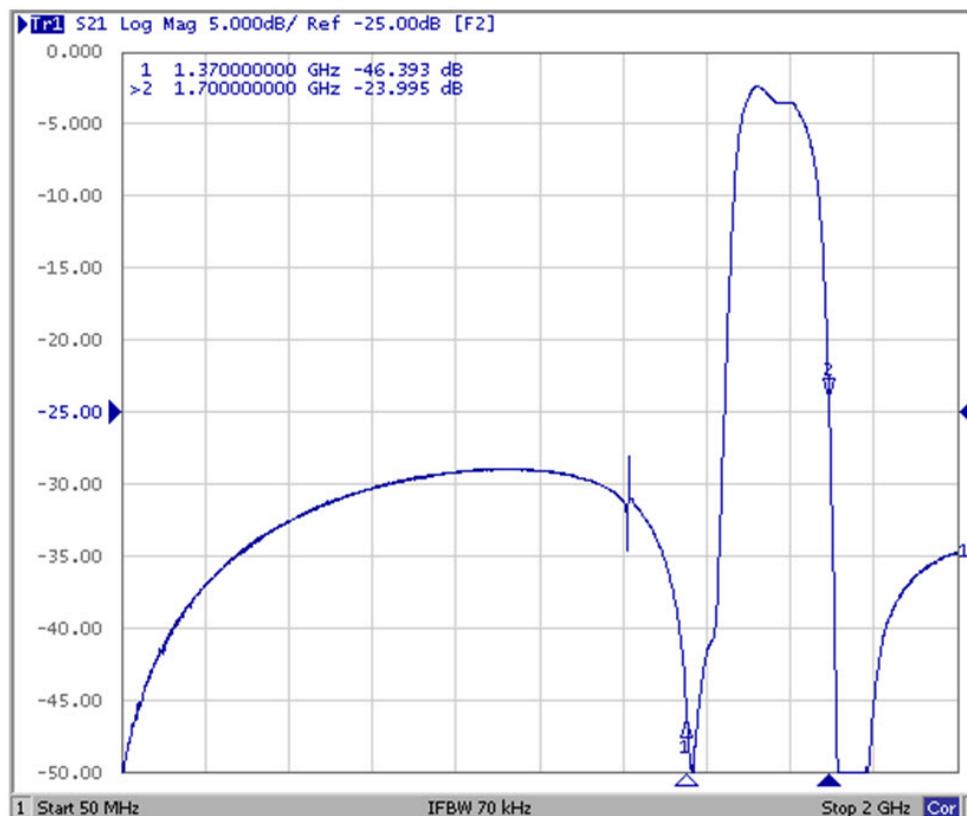
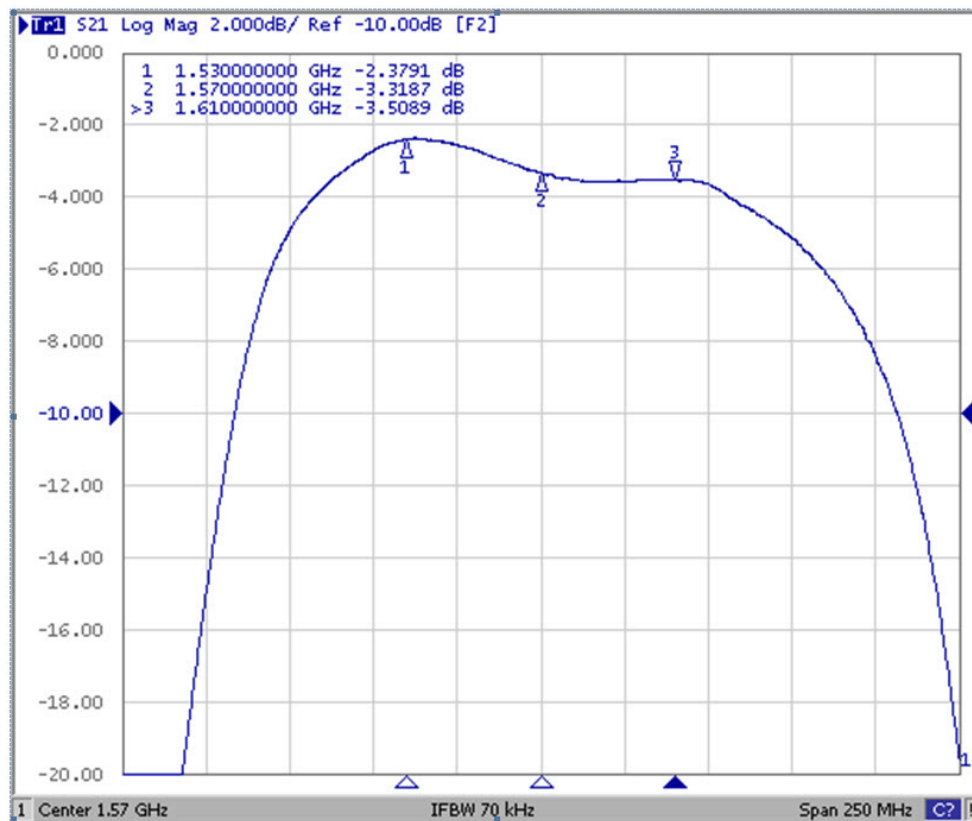


 **CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.**

NOTES:

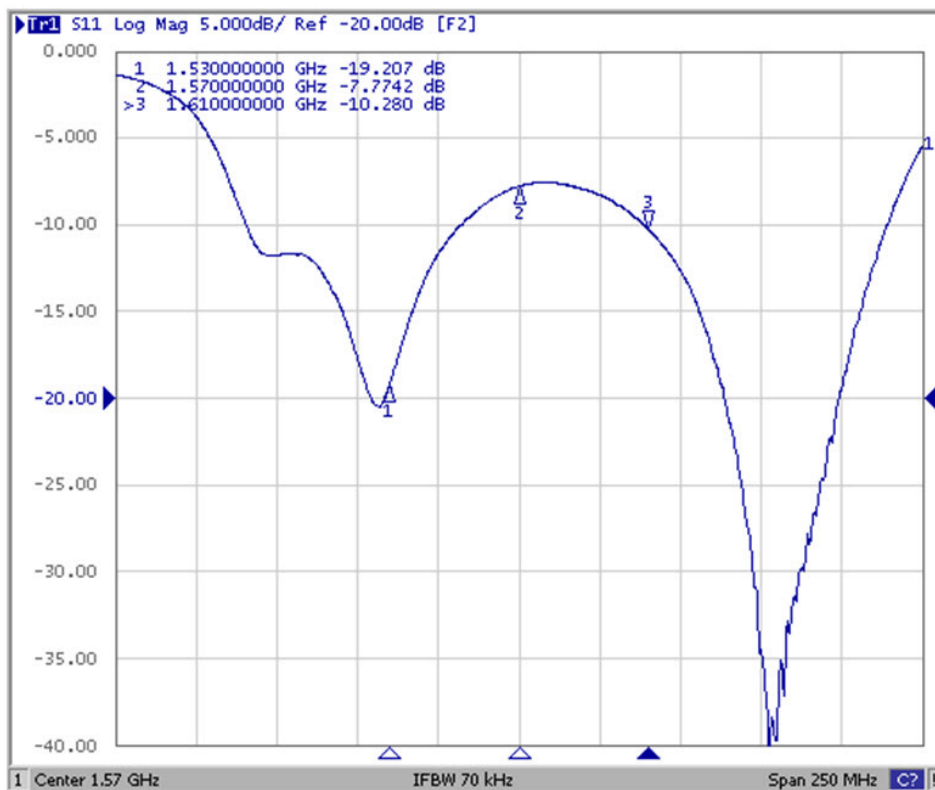
1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

Frequency Characteristics

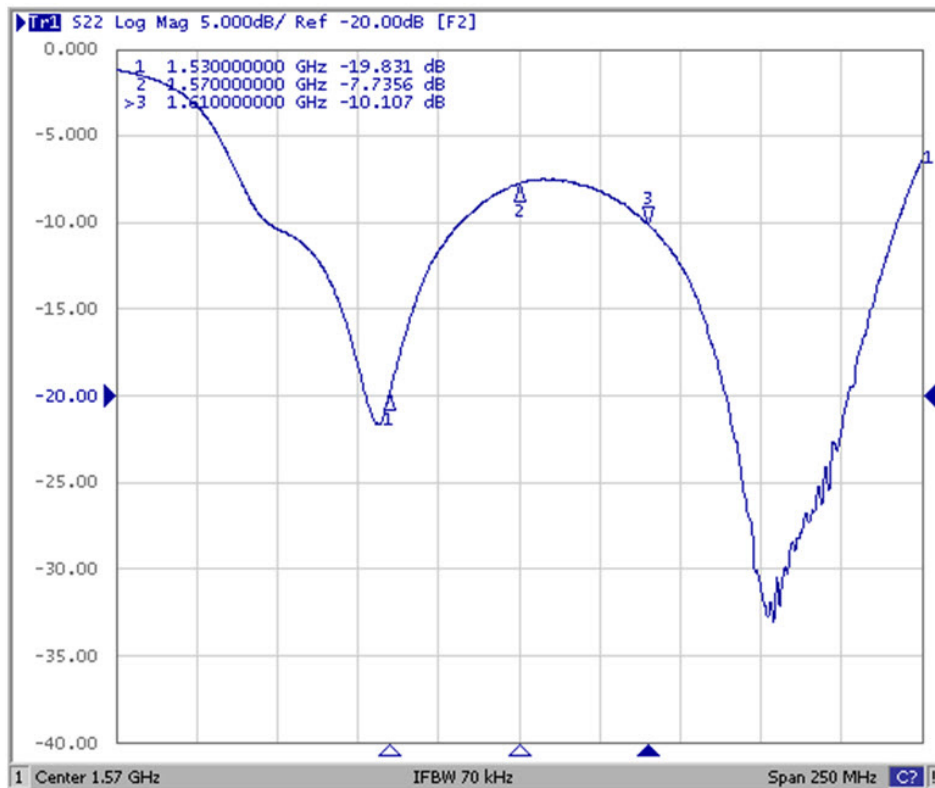


Reflection Functions

S11

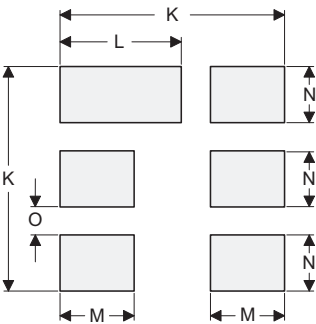
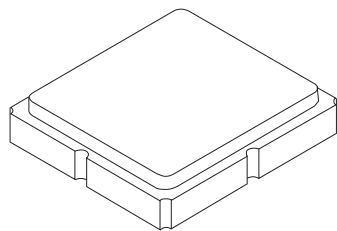


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SM3030-6 Case

6-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint



Case and PCB Footprint Dimensions

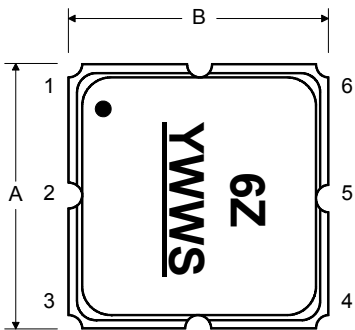
Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.90	3.00	3.10	0.114	0.118	0.122
B	2.90	3.00	3.10	0.114	0.118	0.122
C	-	-	1.40	-	-	0.054
D	0.77	0.90	1.03	0.030	0.035	0.040
E	2.39	2.54	2.69	0.094	0.110	0.105
F	1.45	1.60	1.75	0.057	0.063	0.068
G	0.70	0.85	1.00	0.027	0.033	0.039
H	1.35	1.50	1.65	0.053	0.059	0.064
I	0.45	0.60	0.75	0.017	0.024	0.029
J	1.15	1.30	1.45	0.045	0.051	0.057
K	-	3.20	-	-	0.126	-
L	-	1.70	-	-	0.067	-
M	-	1.05	-	-	0.041	-
N	-	0.81	-	-	0.032	-
O	-	0.38	-	-	0.015	-

Case Materials

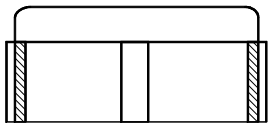
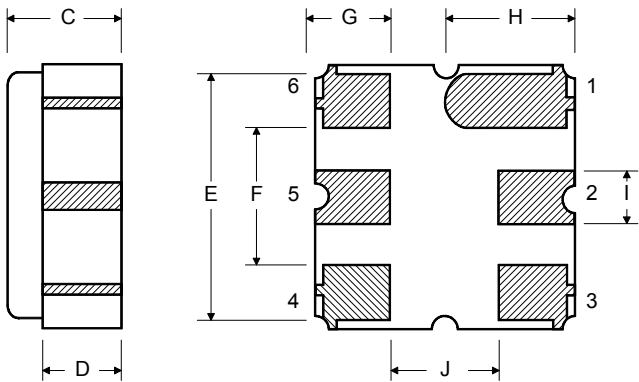
Materials	
Solder Pad Plating	0.3 to 1.0 μ m Gold over 1.27 to 8.89 μ m Nickel
Lid Plating	2.0 to 3.0 μ m Nickel
Body	Al ₂ O ₃ Ceramic

PCB Footprint Top View

TOP VIEW



BOTTOM VIEW



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.

